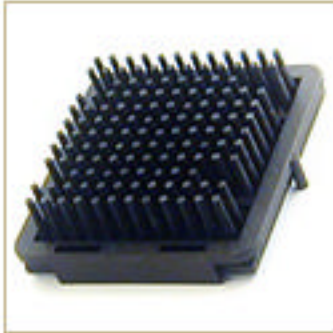




BGA Snap-on Heatsinks

EMULATION TECHNOLOGY, INC.

World Leader in Adapters, Clips, and Test Accessories



Standard BGA product provided as:

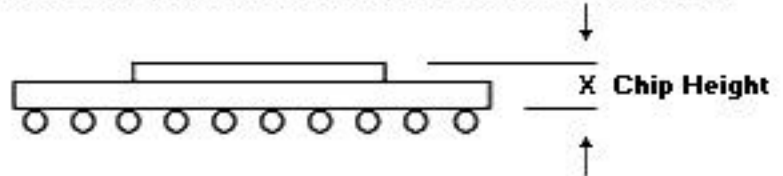
- Black anodized
- Pre-assembled as shown
- Customs available upon request

Other BGA products available:

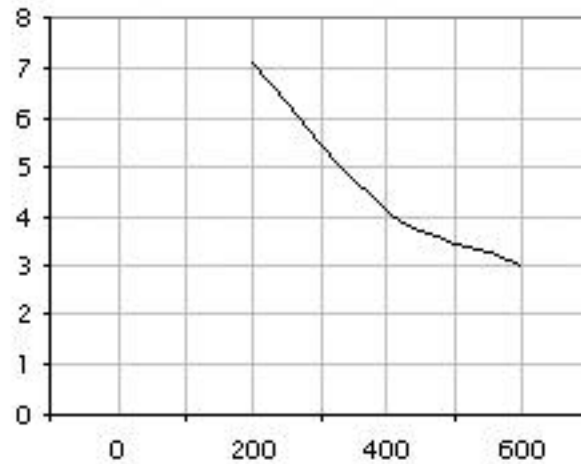
- Rework Stencils
- Reballing Preforms
- Sockets
- Ultra-mini Pogo Pins

ET Part Number	Part Marking	Chip Pkg. Size (sq)	Heatsink Height	Fits Chip Height [x]
H-4003-07-9040-05-A	HS2140DCAB	40 mm	0.3 in (7.62 mm)	1.88 (+/- 0.26) mm
H-4003-08-9040-05-A	HS2081DCAB	40 mm	0.3 in (7.62 mm)	1.38 (+/- 0.26) mm

* Max dimensions include allowance for .005" thick thermal pad



Thermal Resistance from MTG Surface to Ambient [C/Watt]



Air Velocity [ft/min]

— HS2140DCAB HS2081DCAB

EMULATION TECHNOLOGY, INC.

2344 WALSH AVE.

BLDG. F

SANTA CLARA, CA 95051

1-800-ADAPTER (232-7837)

www.1800ADAPTER.com